

# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier



DFN3820A

## LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3 A
$V_{RRM}$	150 V
$I_{FSM}$	80 A
$V_F$ at $I_F = 1.5$ A ( $T_J = 125$ °C)	0.55 V
$T_J$ max.	175 °C
Package	DFN3820A
Circuit configuration	Single

## FEATURES

- Low profile package - typical height of 0.88 mm
- Trench MOS Schottky technology
- Low power losses, high efficiency
- Low forward voltage drop
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code; base P/NHM3
- Compatible to SMP (DO-220AA) package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE  
Available

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in low voltage, high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

## MECHANICAL DATA

**Case:** DFN3820A

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	V3NM153	UNIT
Device marking code		3MP	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}^{(1)}$	3	A
	$I_{F(AV)}^{(2)}$	1.8	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	80	A
Operating junction and storage temperature range	$T_J^{(3)}$	-40 to +175	°C
Operating junction and storage temperature range	$T_{STG}$	-55 to +175	°C

## Notes

- (1) Mounted on 10 mm x 10 mm copper pad area PCB
- (2) Free air, mounted on FR4 PCB, 2 oz., standard footprint
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 1.5\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.69	-	V
	$I_F = 3.0\text{ A}$			0.85	0.97	
	$I_F = 1.5\text{ A}$	$T_J = 125\text{ }^\circ\text{C}$		0.55	-	
	$I_F = 3.0\text{ A}$			0.62	0.68	
Reverse current	$V_R = 100\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.0003	-	mA
		$T_J = 125\text{ }^\circ\text{C}$		0.5	-	
	$V_R = 150\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$		-	0.035	
		$T_J = 125\text{ }^\circ\text{C}$		1.2	3	
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	160	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
(2) Pulse test: pulse width  $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Thermal resistance	$R_{\theta JA}^{(1)(2)}$	135	169	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	5	6.3	

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
(2) Thermal resistance junction-to-ambient to follow JEDEC<sup>®</sup> 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint  
(3) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V3NM153-M3/H	0.023	H	3500	7" diameter plastic tape and reel
V3NM153-M3/I	0.023	I	14 000	13" diameter plastic tape and reel
V3NM153HM3/H <sup>(1)</sup>	0.023	H	3500	7" diameter plastic tape and reel
V3NM153HM3/I <sup>(1)</sup>	0.023	I	14 000	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

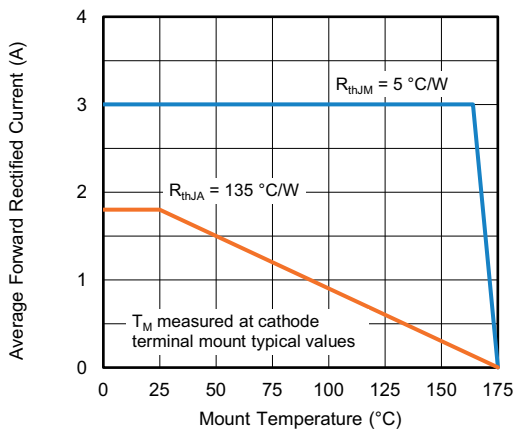


Fig. 1 - Maximum Forward Current Derating Curve

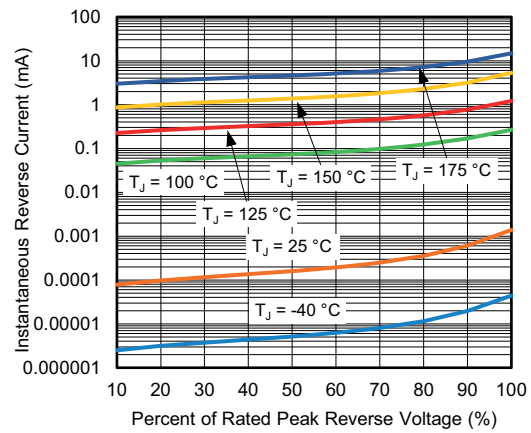


Fig. 4 - Typical Reverse Characteristics

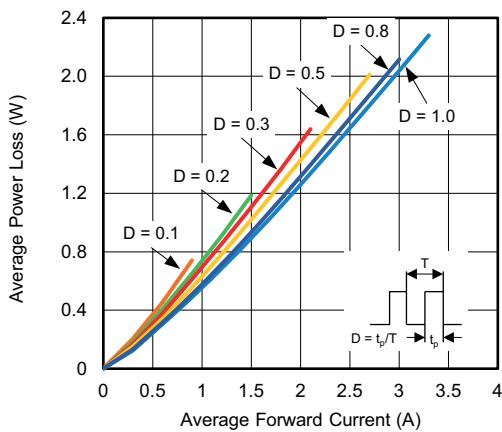


Fig. 2 - Forward Power Loss Characteristics

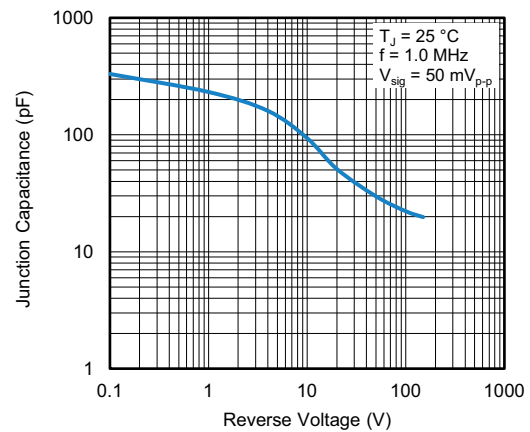


Fig. 5 - Typical Junction Capacitance

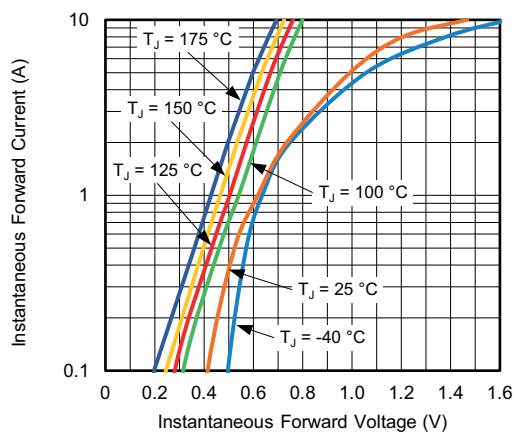


Fig. 3 - Typical Instantaneous Forward Characteristics

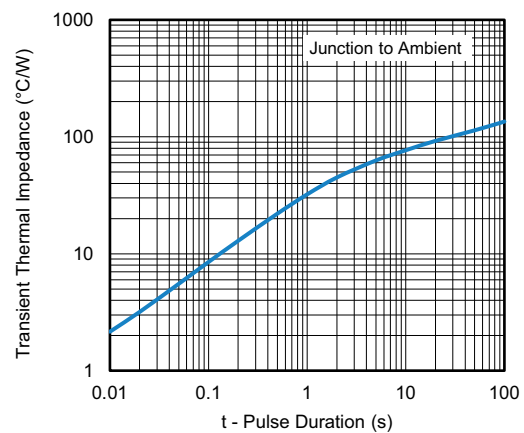


Fig. 6 - Typical Transient Thermal Impedance





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